

**Amendments to the Claims:**

This listing of claims will replace all prior versions, and listings, of claims in the application:

**Listing of Claims:**

1. (Currently amended) An electronic microcircuit module tape including a substrate, at least one contact area on a first face of this substrate, a second face of this substrate capable of accommodating an integrated circuit, ~~characterised in that it~~ wherein the tape further includes a ~~parallelepiped shape~~, a first adhesive means to retain a first face of a mask in position against the second face of the substrate, and wherein the mask ~~delimiting the parallelepiped being~~ is perforated to form a window around the integrated circuit ~~and a second adhesive means dispensed on a second face of the mask.~~

2. (Currently amended) The electronic microcircuit module tape according to claim 1, ~~characterised in that~~ wherein the mask is made from a material identical to that of a card body provided to receive the module, ~~for example from a polymer of polyester or polyvinyl chloride type.~~

3. (Currently amended) The electronic microcircuit module tape according to claim 1, ~~characterised in that~~ wherein the mask has a thickness, defined with regard to the second face of the substrate on which it is mounted, greater than the height of the integrated circuit.

4. (Currently amended) The electronic microcircuit module tape according to claim 1, ~~characterised in that~~ wherein the first

adhesive means enables the integrated circuit to be retained on the substrate.

5. (Withdrawn) A method for conditioning an electronic microcircuit module, characterised in that it includes the following stages consisting of

creating a contact area on a first face of a substrate tape,

arranging a first adhesive means between a second face of the substrate and a first face of a mask tape, to keep the mask in position against the second face,

perforating the mask tape so that a mask window is facing the contact area, and

arranging a second adhesive means on the second face of the mask.

6. (Withdrawn) The method according to claim 5, characterised in that it includes an additional stage consisting of:

choosing a mask in a material identical to that of a card on which the module is to be mounted.

7. (Withdrawn) The method according to claim 5, characterised in that the mask has the form of a tape including several windows which are laminated on a support including several contact area before separation into individual units.

8. (Withdrawn) The method according to claim 5, characterised in that the stage consisting in retaining the mask in position

against the second face of the substrate includes an operation consisting of:

laminating the first adhesive means on this second face of the substrate.

9. (Withdrawn) The method according to claim 5, characterised in that the stage consisting in arranging an adhesive means on the mask includes an operation consisting of

depositing the adhesive means on the mask, and then

perforating this mask before laminating it against the second face of the substrate.

10. (Withdrawn) The method according to claim 5, characterised in that it includes a subsequent stage consisting in gluing an integrated circuit to the second face of the substrate, on the first adhesive means.

11. (Withdrawn) The method according to claim 5, characterised in that it includes a stage consisting of:

gluing the mask equipped with an electronic circuit to the bottom of a card recess.

12. (Withdrawn) The method according to claim 11, characterised in that the stage consisting in gluing the mask to the recess includes an operation consisting of:

depositing cyanoacrylate glue between the mask and the bottom of the recess.

13. (Withdrawn) The method according to claim 11, characterised in that the stage consisting in gluing the mask into the recess includes an operation consisting of:

soldering by emission of ultrasound waves.

14. (Withdrawn) The method according to claim 5 further comprising separating the individual module in the form of a parallelepiped.

15. (New) The electronic microcircuit module tape of claim 1 further comprising a second adhesive means dispensed on a second face of the mask.